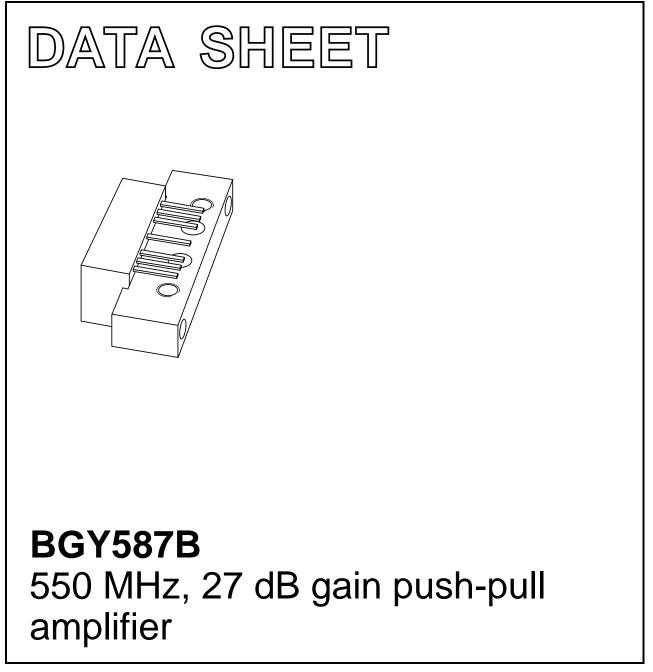
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1997 Apr 10 2001 Oct 22



2001 Oct 22

# 550 MHz, 27 dB gain push-pull amplifier

## FEATURES

- Excellent linearity
- Extremely low noise
- Silicon nitride passivation
- Rugged construction
- TiPtAu metallized crystals ensure optimal reliability.

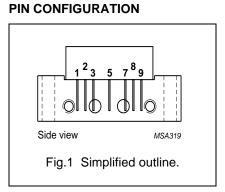
### DESCRIPTION

Hybrid amplifier module for CATV systems operating over a frequency range of 40 to 550 MHz at a voltage supply of +24 V (DC).

## QUICK REFERENCE DATA

Р	INI	ΝIN	G -	· S(	ОΤ	11	5J

PIN	DESCRIPTION
1	input
2	common
3	common
5	+V <sub>B</sub>
7	common
8	common
9	output



SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G <sub>p</sub>	power gain	f = 50 MHz	26.2	27.8	dB
		f = 550 MHz	27.5	-	dB
I <sub>tot</sub>	total current consumption (DC)	V <sub>B</sub> = +24 V	-	340	mA

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
Vi	RF input voltage	-	55	dBmV
T <sub>stg</sub>	storage temperature		+100	°C
T <sub>mb</sub>	operating mounting base temperature		+100	°C
V <sub>B</sub>	DC supply voltage		+28	V

**BGY587B** 

## BGY587B

#### CHARACTERISTICS

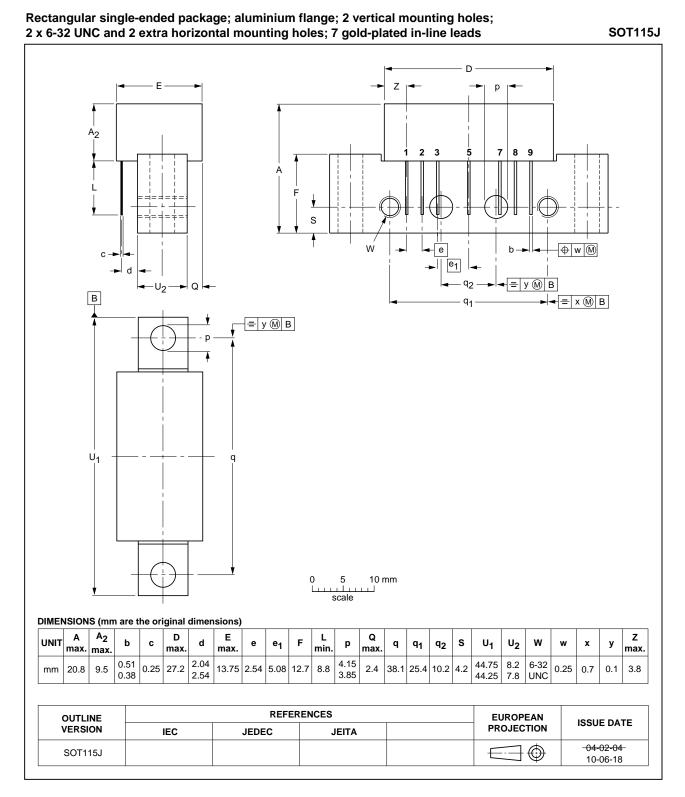
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G <sub>p</sub>	power gain	f = 50 MHz	26.2	27.8	dB
		f = 550 MHz	27.5		dB
SL	slope cable equivalent	f = 40 to 550 MHz	0.5	2.5	dB
FL	flatness of frequency response	f = 40 to 550 MHz	-	±0.4	dB
S <sub>11</sub>	input return losses	f = 40 to 80 MHz	20	_	dB
		f = 80 to 160 MHz	19	-	dB
		f = 160 to 550 MHz	18	_	dB
S <sub>22</sub>	output return losses	f = 40 to 80 MHz	20	_	dB
		f = 80 to 160 MHz	19	-	dB
		f = 160 to 550 MHz	18	_	dB
СТВ	composite triple beat	77 channels flat; $V_0 = 44 \text{ dBmV}$ ; measured at 547.25 MHz	-	-57	dB
X <sub>mod</sub>	cross modulation	77 channels flat; $V_0 = 44 \text{ dBmV}$ ; measured at 55.25 MHz	-	-60	dB
CSO	composite second order distortion	77 channels flat; $V_0 = 44 \text{ dBmV}$ ; measured at 548.5 MHz	-	-57	dB
d <sub>2</sub>	second order distortion	note 1	-	-68	dB
Vo	output voltage	d <sub>im</sub> = -60 dB; note 2	61	-	dBmV
F	noise figure	f = 550 MHz	-	6.5	dB
I <sub>tot</sub>	total current consumption	DC value; V <sub>B</sub> = +24 V; note 3	-	340	mA

#### Notes

- 1.  $f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV}; f_q = 493.25 \text{ MHz}; V_q = 44 \text{ dBmV}; measured at f_p + f_q = 548.5 \text{ MHz}.$
- 2. Measured according to DIN45004B;  $f_p = 540.25 \text{ MHz}; V_p = V_o = 66.5 \text{ dBmV};$   $f_q = 547.25 \text{ MHz}; V_q = V_o - 6 \text{ dB};$   $f_r = 549.25 \text{ MHz}; V_r = V_o - 6 \text{ dB};$ measured at  $f_p + f_q - f_r = 538.25 \text{ MHz}.$
- 3. The module normally operates at  $V_B$  = +24 V, but is able to withstand supply transients up to +30 V.

#### PACKAGE OUTLINE

**NXP Semiconductors** 



## BGY587B

## BGY587B

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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## BGY587B

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#### **Contact information**

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